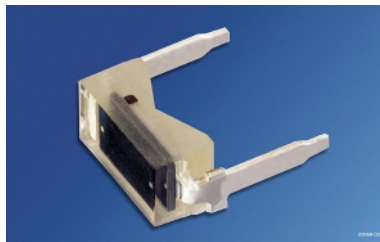
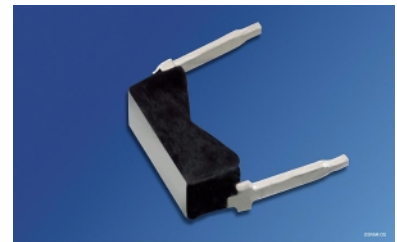


# Silizium-Fotodiode Silicon Photodiode

## BPX 90 BPX 90 F



BPX 90



BPX 90 F

### Wesentliche Merkmale

- Speziell geeignet für Anwendungen im Bereich von 400 nm bis 1100 nm (BPX 90) und bei 950 nm (BPX 90 F)
- Hohe Fotoempfindlichkeit
- DIL-Plastikbauform mit hoher Packungsdichte

### Anwendungen

- Industrieelektronik
- „Messen/Steuern/Regeln“

### Features

- Especially suitable for applications from 400 nm to 1100 nm (BPX 90) and of 950 nm (BPX 90 F)
- High photosensitivity
- DIL plastic package with high packing density

### Applications

- Industrial electronics
- For control and drive circuits

Typ Type	Bestellnummer Ordering Code
BPX 90	Q62702-P47
BPX 90 F	Q62702-P928

**Grenzwerte  
Maximum Ratings**

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Betriebs- und Lagertemperatur Operating and storage temperature range	$T_{op}; T_{stg}$	- 40 ... + 80	°C
Löttemperatur (Lötstelle 2 mm vom Gehäuse entfernt bei Lötzeit $t \leq 3$ s) Soldering temperature in 2 mm distance from case bottom ( $t \leq 3$ s)	$T_S$	230	°C
Sperrspannung Reverse voltage	$V_R$	32	V
Verlustleistung, $T_A = 25$ °C Total power dissipation	$P_{tot}$	100	mW

**Kennwerte  $T_A = 25$  °C  
Characteristics**

Bezeichnung Parameter	Symbol Symbol	Wert Value		Einheit Unit
		BPX 90	BPX 90 F	
Fotostrom Photocurrent $V_R = 5$ V, Normlicht/standard light A, $T = 2856$ K, $E_V = 1000$ lx $V_R = 5$ V, $\lambda = 950$ nm, $E_e = 1$ mW/cm <sup>2</sup>	$I_P$	45 ( $\geq 32$ )	–	$\mu$ A
	$I_P$	–	26 ( $\geq 16$ )	$\mu$ A
Wellenlänge der max. Fotoempfindlichkeit Wavelength of max. sensitivity	$\lambda_{S\ max}$	830	950	nm
Spektraler Bereich der Fotoempfindlichkeit $S = 10\%$ von $S_{max}$ Spectral range of sensitivity $S = 10\%$ of $S_{max}$	$\lambda$	400 ... 1150	800 ... 1150	nm
Bestrahlungsempfindliche Fläche Radiant sensitive area	$A$	5.5	5.5	mm <sup>2</sup>
Abmessung der bestrahlungsempfindlichen Fläche Dimensions of radiant sensitive area	$L \times B$ $L \times W$	1.75 × 3.15	1.75 × 3.15	mm × mm
Abstand Chipoberfläche zu Gehäuseoberfläche Distance chip front to case surface	$H$	0.5	0.5	mm
Halbwinkel Half angle	$\varphi$	$\pm 60$	$\pm 60$	Grad deg.

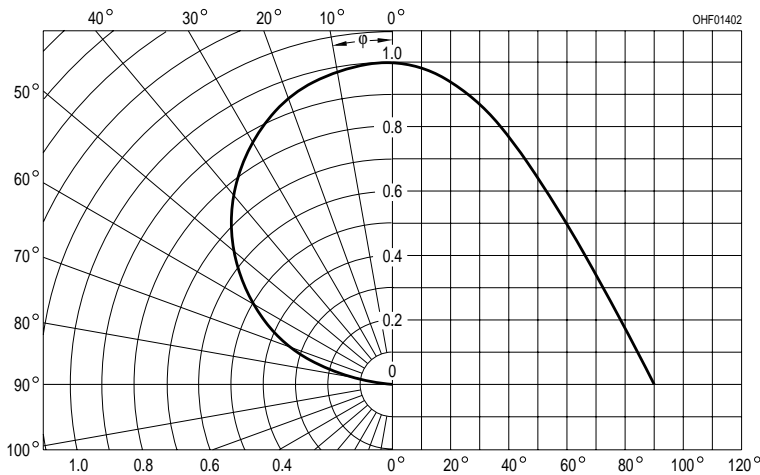
**Kennwerte  $T_A = 25\text{ °C}$**   
**Characteristics (cont'd)**

Bezeichnung Parameter	Symbol Symbol	Wert Value		Einheit Unit
		BPX 90	BPX 90 F	
Dunkelstrom, $V_R = 10\text{ V}$ Dark current	$I_R$	5 ( $\leq 180$ )	5 ( $\leq 180$ )	nA
Spektrale Fotoempfindlichkeit, $\lambda = 950\text{ nm}$ Spectral sensitivity	$S_\lambda$	0.48	0.48	A/W
Quantenausbeute, $\lambda = 950\text{ nm}$ Quantum yield	$\eta$	0.62	0.62	<u>Electrons</u> Photon
Leerlaufspannung Open-circuit voltage $E_v = 1000\text{ lx}$ , Normlicht/standard light A, $T = 2856\text{ K}$ $E_e = 0.5\text{ mW/cm}^2$ , $\lambda = 950\text{ nm}$	$V_O$  $V_O$	450 ( $\geq 380$ ) –	– 400 ( $\geq 340$ )	mV mV
Kurzschlußstrom Short-circuit current $E_v = 1000\text{ lx}$ , Normlicht/standard light A, $T = 2856\text{ K}$ $E_e = 0.5\text{ mW/cm}^2$ , $\lambda = 950\text{ nm}$	$I_{SC}$  $I_{SC}$	45 –	– 13	$\mu\text{A}$ $\mu\text{A}$
Anstiegs- und Abfallzeit des Fotostromes Rise and fall time of the photocurrent $R_L = 1\text{ k}\Omega$ ; $V_R = 5\text{ V}$ ; $\lambda = 850\text{ nm}$ ; $I_p = 30\text{ }\mu\text{A}$	$t_r, t_f$	1.3	1.3	$\mu\text{s}$
Durchlaßspannung, $I_F = 80\text{ mA}$ , $E = 0$ Forward voltage	$V_F$	1.3	1.3	V
Kapazität, $V_R = 0\text{ V}$ , $f = 1\text{ MHz}$ , $E = 0$ Capacitance	$C_0$	430	430	pF

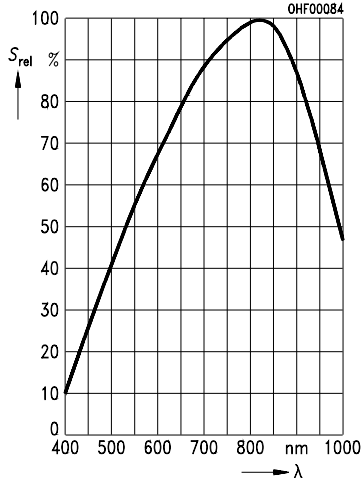
**Kennwerte**  $T_A = 25\text{ °C}$   
**Characteristics** (cont'd)

Bezeichnung Parameter	Symbol Symbol	Wert Value		Einheit Unit
		BPX 90	BPX 90 F	
Temperaturkoeffizient von $V_O$ Temperature coefficient of $V_O$	$TC_V$	- 2.6	- 2.6	mV/K
Temperaturkoeffizient von $I_{SC}$ Temperature coefficient of $I_{SC}$ Normlicht/standard light A $\lambda = 950\text{ nm}$	$TC_I$ $TC_I$	0.18 -	- 0.2	%/K %/K
Rauschäquivalente Strahlungsleistung Noise equivalent power $V_R = 10\text{ V}, \lambda = 950\text{ nm}$	$NEP$	$8 \times 10^{-14}$	$8 \times 10^{-14}$	$\frac{W}{\sqrt{Hz}}$
Nachweisgrenze, $V_R = 10\text{ V}, \lambda = 950\text{ nm}$ Detection limit	$D^*$	$2.9 \times 10^{12}$	$2.9 \times 10^{12}$	$\frac{cm \times \sqrt{Hz}}{W}$

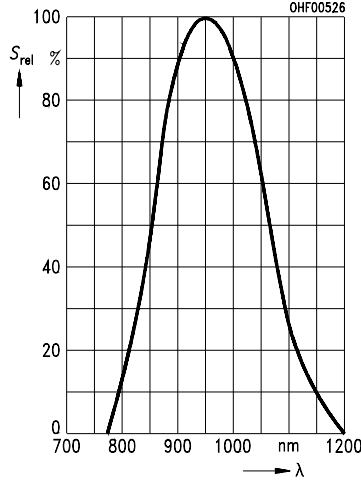
**Directional Characteristics**  $S_{rel} = f(\varphi)$



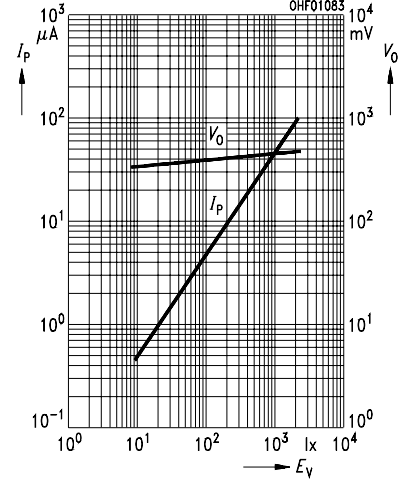
**Relative Spectral Sensitivity**  
BPX 90  $S_{rel} = f(\lambda)$



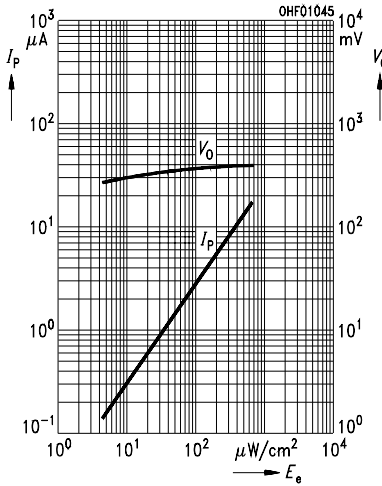
**Relative Spectral Sensitivity**  
BPX 90 F  $S_{rel} = f(\lambda)$



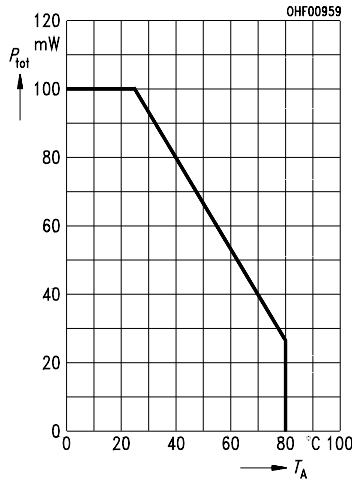
**Photocurrent  $I_P = f(E_v)$ ,  $V_R = 5 V$**   
**Open-Circuit Volt. BPX 90  $V_O = f(E_v)$**



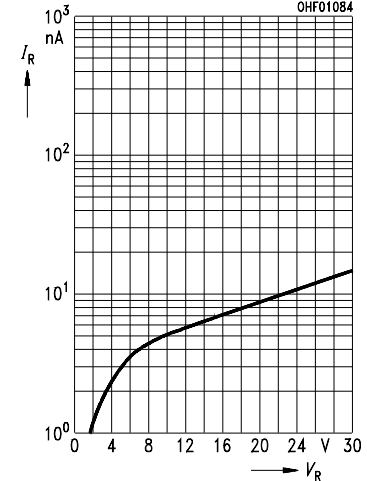
**Photocurrent  $I_P = f(E_e)$ ,  $V_R = 5 V$**   
**Open-Circuit Voltage  $V_O = f(E_e)$**   
BPX 90 F



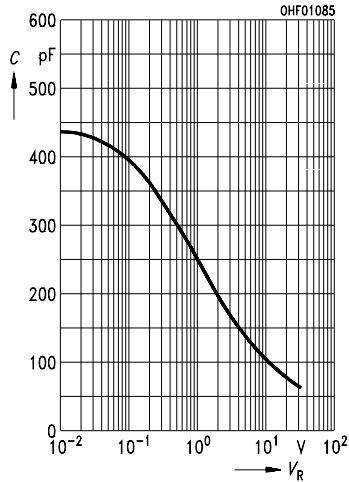
**Total Power Dissipation**  
 $P_{tot} = f(T_A)$



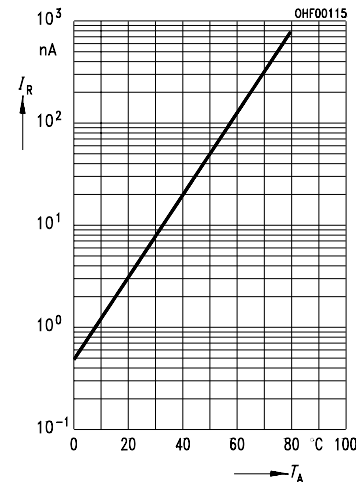
**Dark Current**  
 $I_R = f(V_R), E = 0$



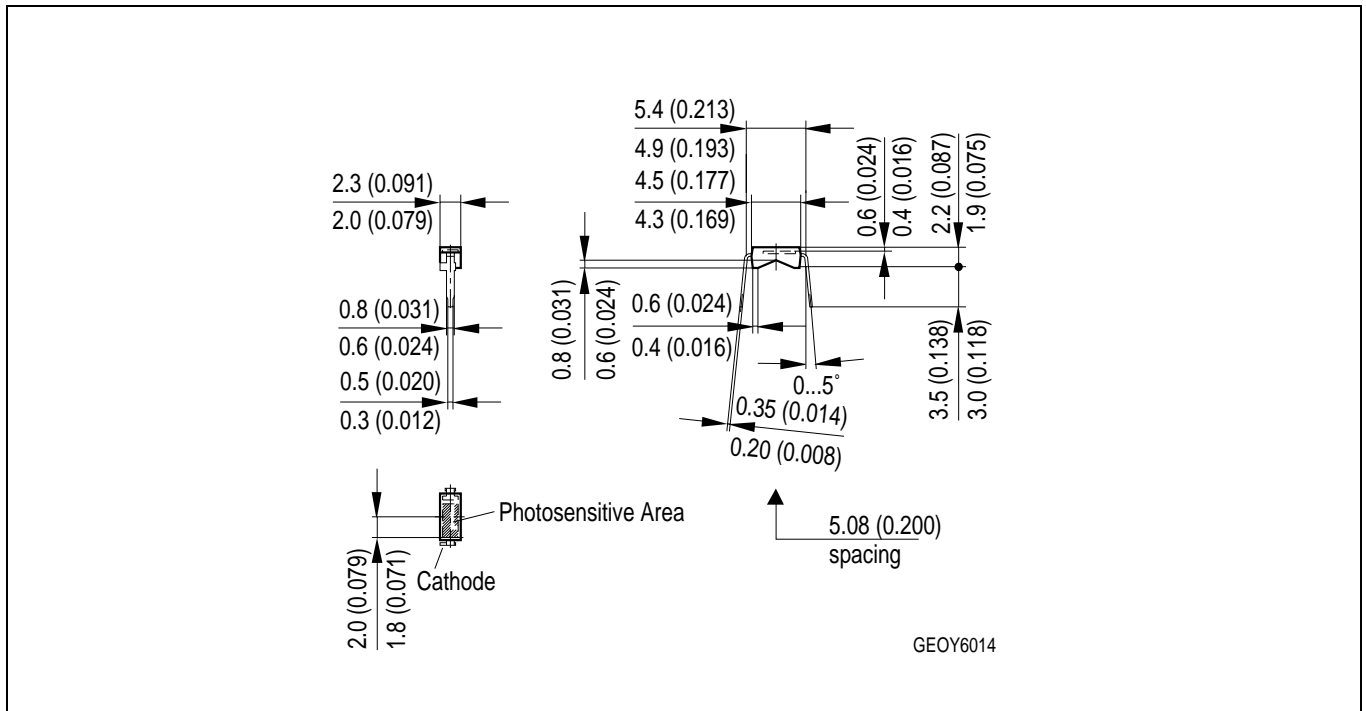
**Capacitance**  
 $C = f(V_R), f = 1 MHz, E = 0$



**Dark Current**  
 $I_R = f(T_A), V_R = 10 V, E = 0$



**Maßzeichnung  
Package Outlines**



Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

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**Packing**

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

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<sup>1</sup> A critical component is a component used in a life-support device or system whose failure can reasonably be expected to cause the failure of that life-support device or system, or to affect its safety or effectiveness of that device or system.

<sup>2</sup> Life support devices or systems are intended (a) to be implanted in the human body, or (b) to support and/or maintain and sustain human life. If they fail, it is reasonable to assume that the health of the user may be endangered.